

FIGURE 1  
PRIOR ART

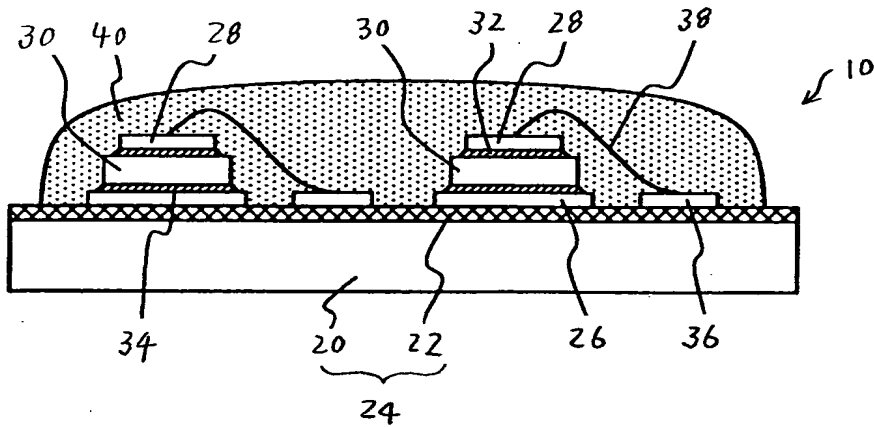


FIGURE 2  
PRIOR ART

10022297.121201

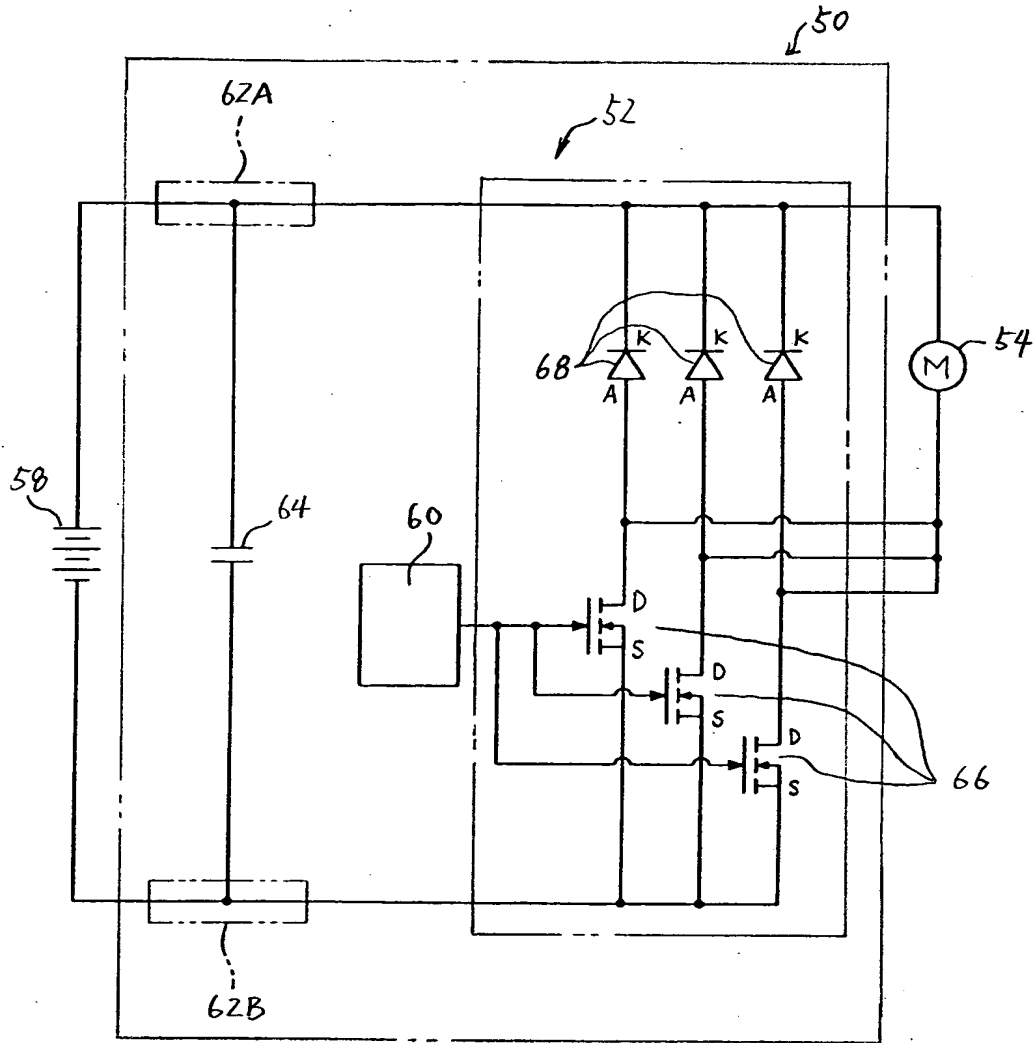


FIGURE 3

40622297 121201

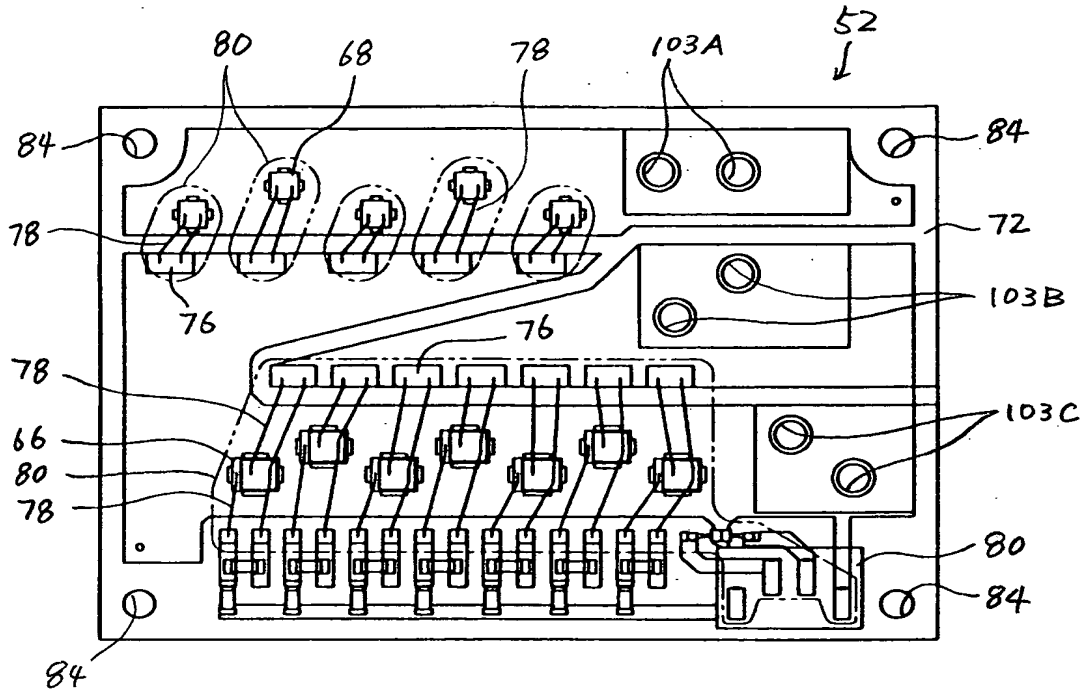


FIGURE 4

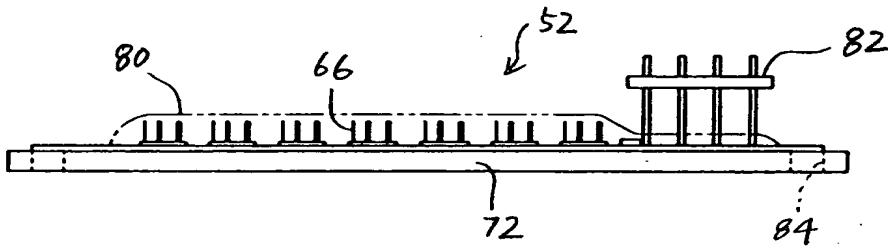


FIGURE 5

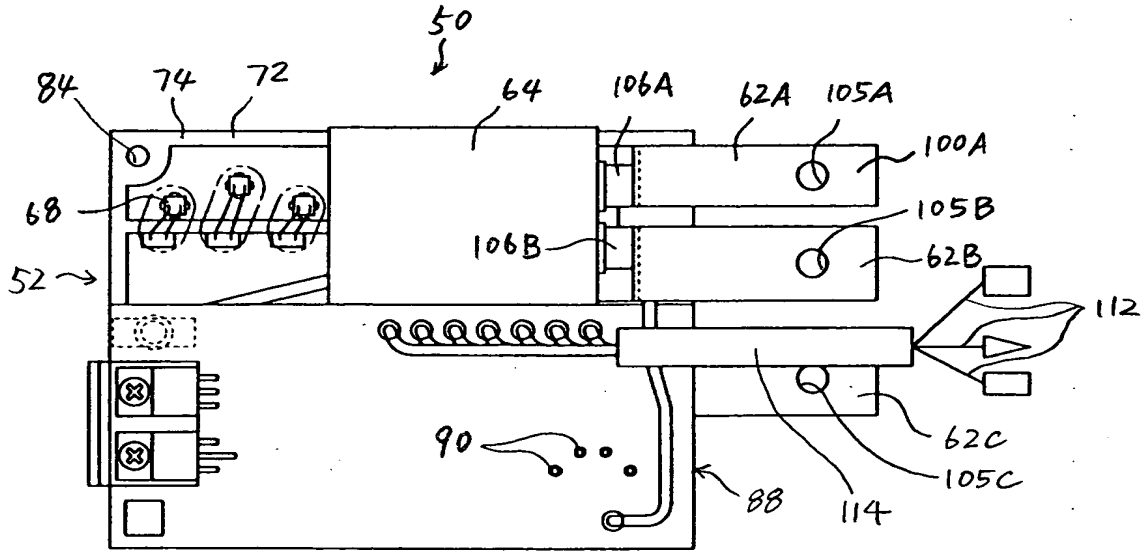


FIGURE 6

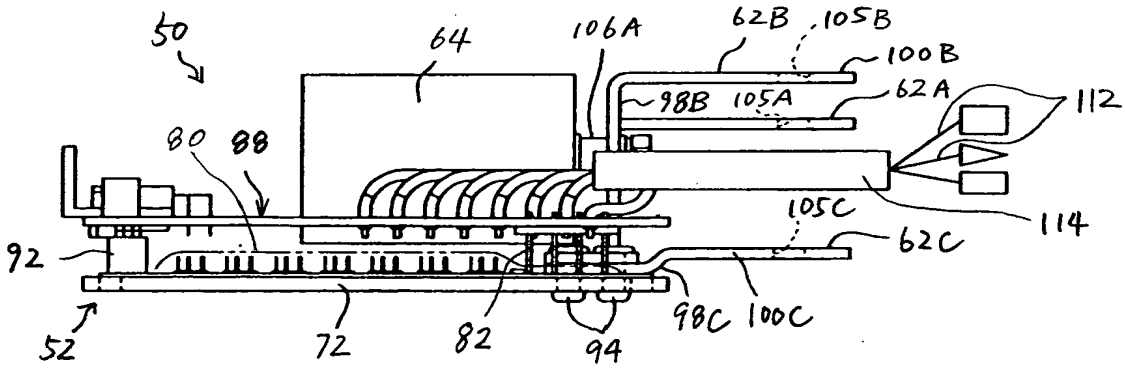


FIGURE 7

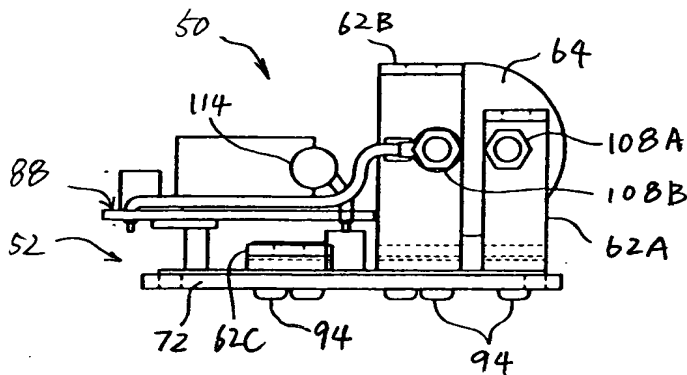


FIGURE 8

1002297 121201

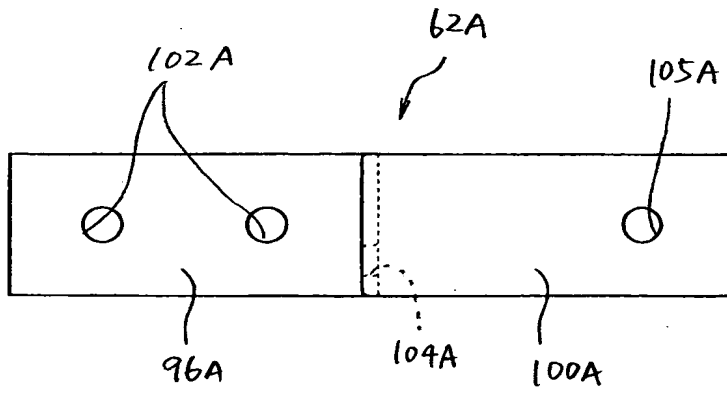


FIGURE 9

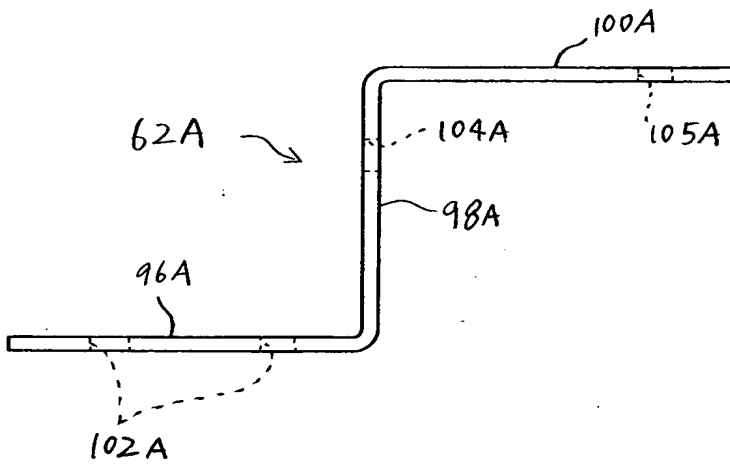


FIGURE 10

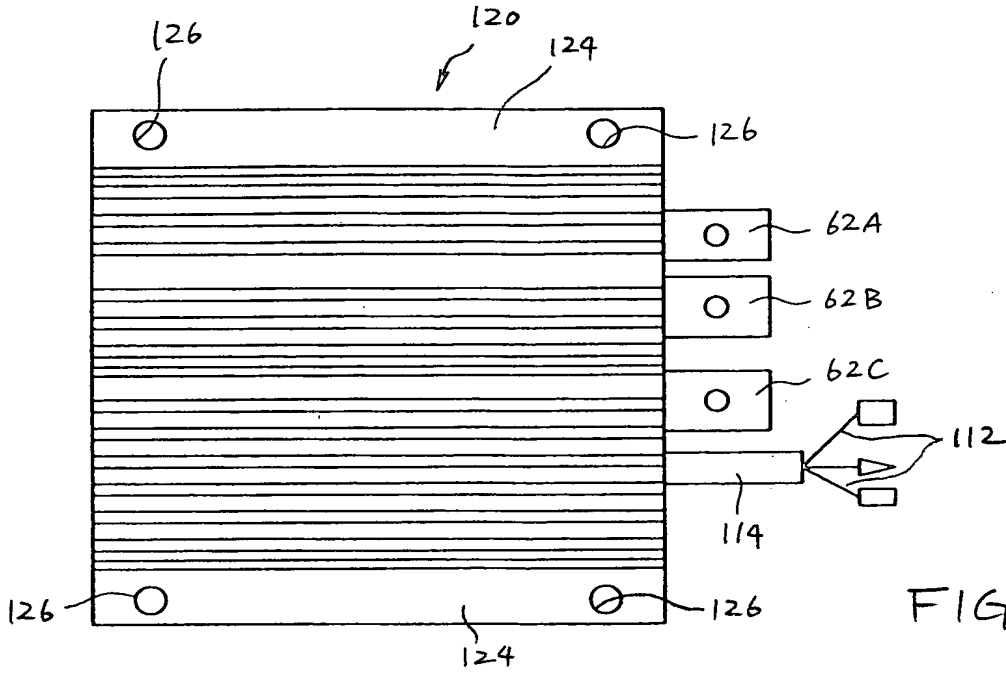


FIGURE 11

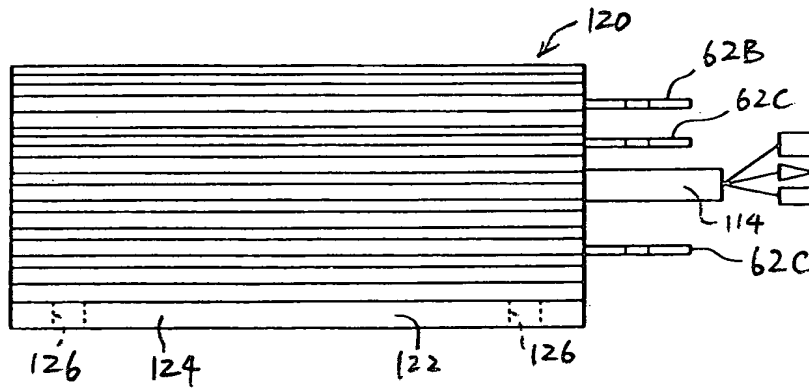


FIGURE 12

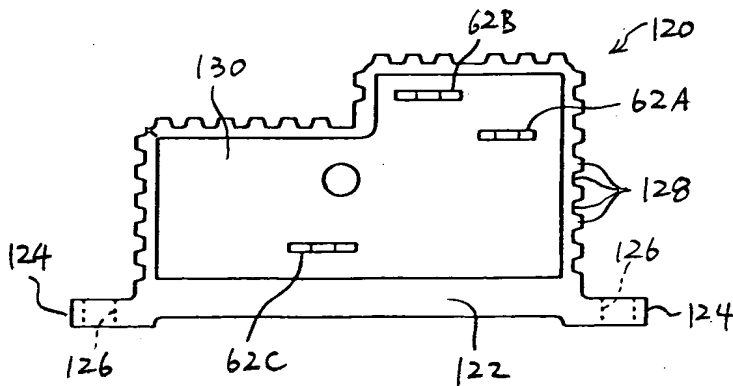


FIGURE 13

10022297.121201

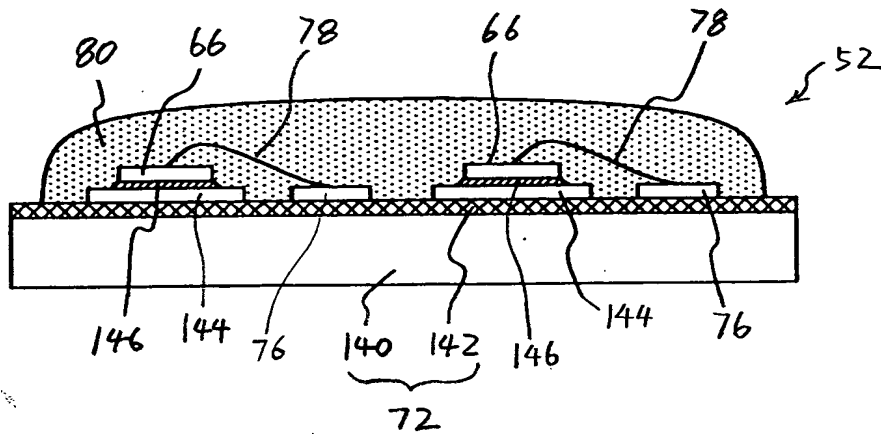


FIGURE 14

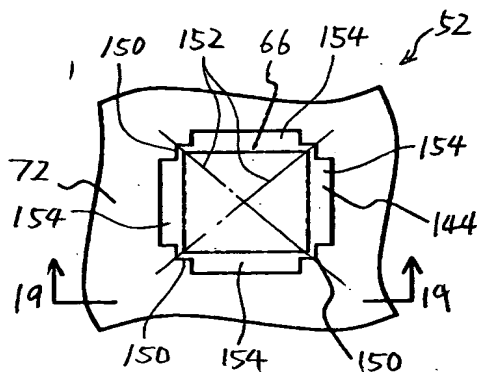


FIGURE 15

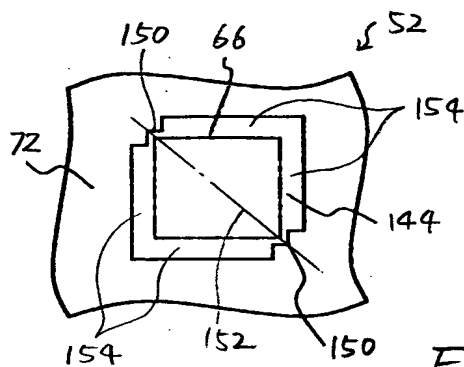


FIGURE 16

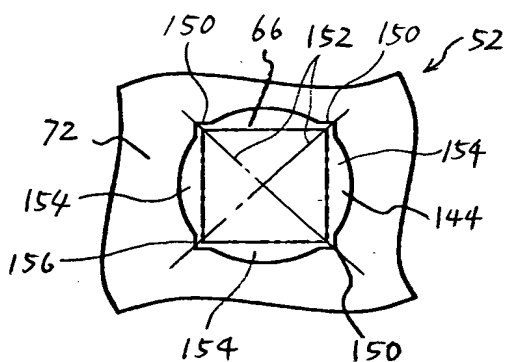


FIGURE 17

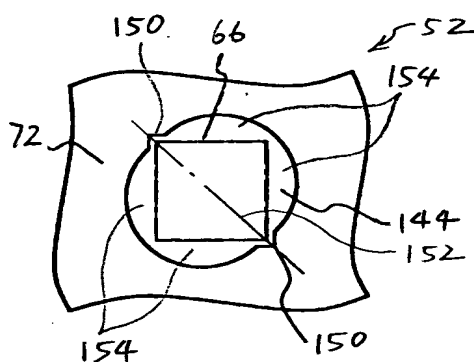


FIGURE 18

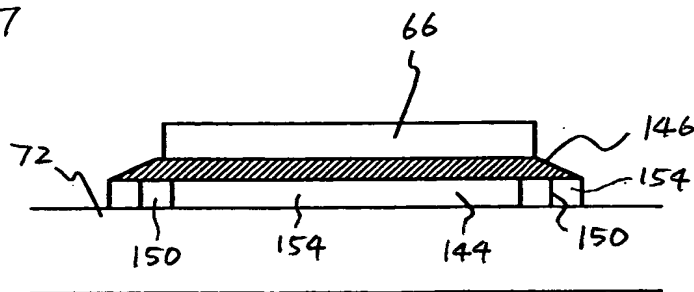


FIGURE 19



# REFLOW SOLDERING DEVICE

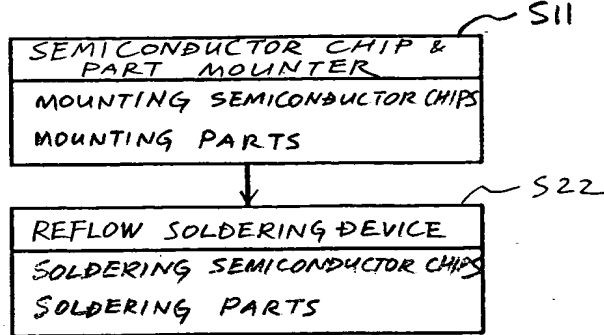


FIGURE 20

# REFLOW SOLDERING DEVICE + DIE BONDER

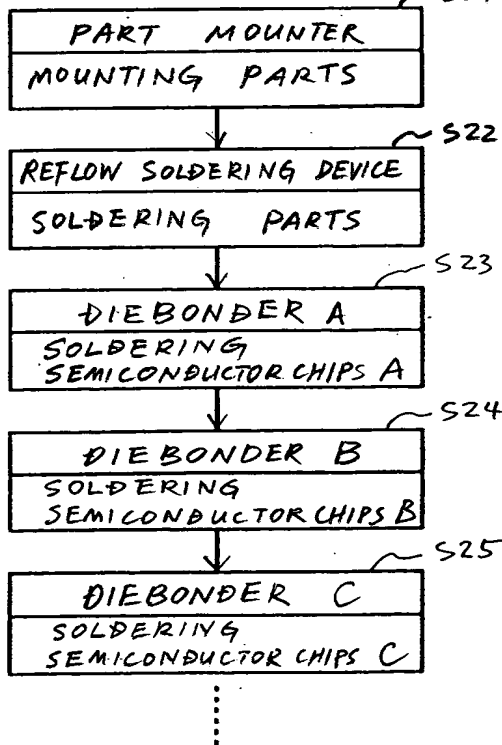


FIGURE 21

# REFLOW SOLDERING DEVICE (USING MOUNTING JIG FOR SEMICONDUCTOR CHIPS)

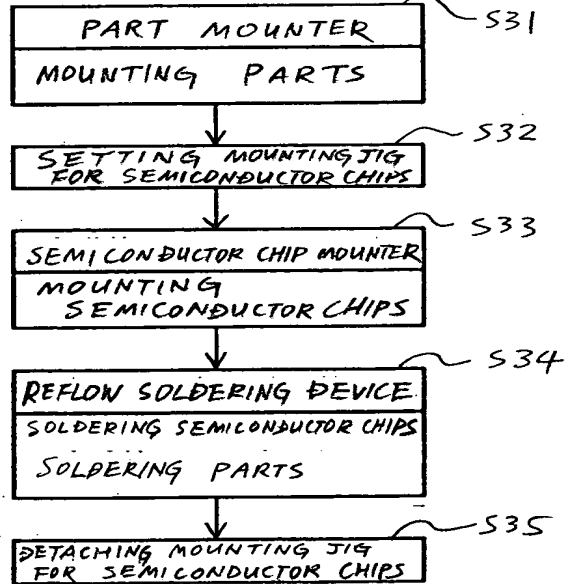


FIGURE 22

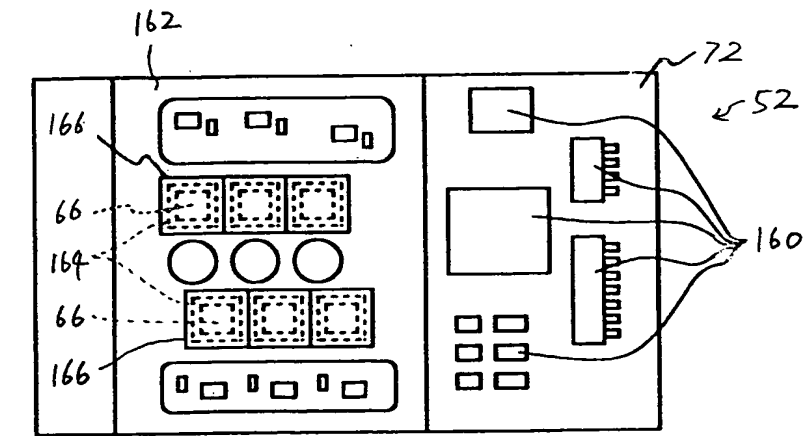


FIGURE 23

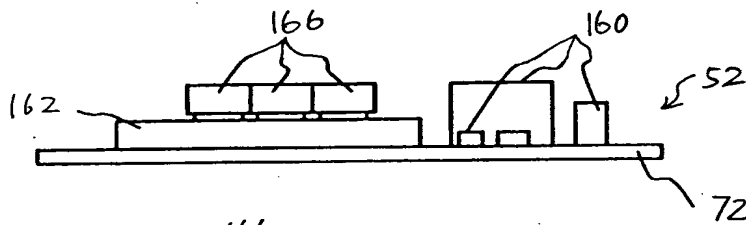


FIGURE 24

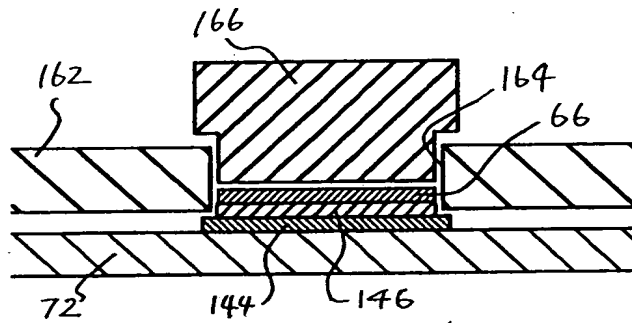


FIGURE 25

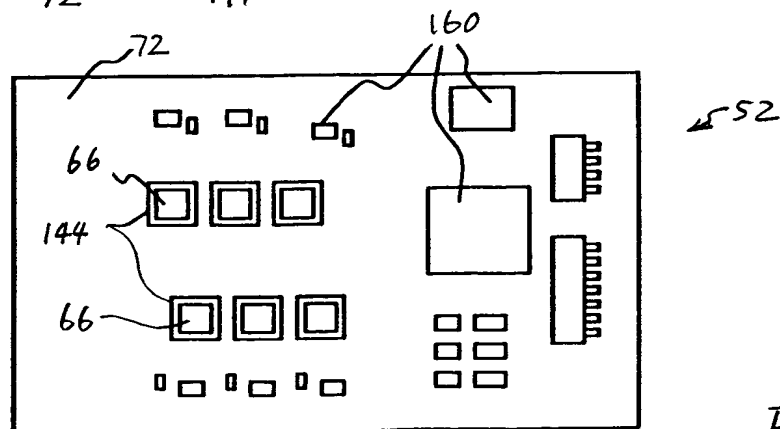


FIGURE 26